

SLVS165H - APRIL 1998 - REVISED JULY 2012

PROCESSOR SUPERVISORY CIRCUITS

FEATURES

- Power-On Reset Generator With Fixed Delay Time of 200 ms (TPS3823/4/5/8) or 25 ms (TPS3820)
- Manual Reset Input (TPS3820/3/5/8)
- Reset Output Available in Active-Low (TPS3820/3/4/5), Active-High (TPS3824/5) and Open-Drain (TPS3828)
- Supply Voltage Supervision Range:
 2.5 V, 3 V, 3.3 V, 5 V
- Watchdog Timer (TPS3820/3/4/8)
- Supply Current of 15 μA (Typ)
- SOT23-5 Package
- Temperature Range: -40°C to +85°C

APPLICATIONS

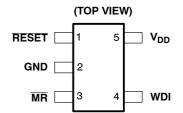
- Applications Using DSPs, Microcontrollers, or Microprocessors
- Industrial Equipment
- Programmable Controls
- Automotive Systems
- Portable/Battery-Powered Equipment
- Intelligent Instruments
- Wireless Communications Systems
- Notebook/Desktop Computers

DESCRIPTION

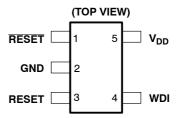
The TPS382x family of supervisors provide circuit initialization and timing supervision, primarily for DSP and processor-based systems. During power-on, RESET asserts when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors V_{DD} and keeps $\overline{\text{RESET}}$ active as long as V_{DD} remains below the threshold voltage, V_{IT-} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, t_{d} , starts after V_{DD} has risen above the threshold voltage, V_{IT-} . When the supply voltage drops below the threshold voltage V_{IT-} , the output becomes

active (low) again. No external components are required. All the devices of this family have a fixed-sense threshold voltage, V_{IT-} , set by an internal voltage divider.

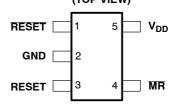
TPS3820, TPS3823, TPS3828: DBV PACKAGE TPS3820A, TPS3823A, TPS3828A: DBV PACKAGE



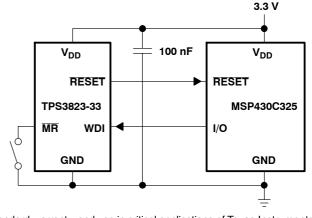
TPS3824 and TPS3824A: DBV PACKAGE



TPS3825 and TPS3825A: DBV PACKAGE (TOP VIEW)



TYPICAL APPLICATION





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DESCRIPTION (Continued)

The TPS3820/3/5/8 devices incorporate a manual reset input, $\overline{\text{MR}}$. A low level at $\overline{\text{MR}}$ causes $\overline{\text{RESET}}$ to become active. The TPS3824/5 devices include a high-level output RESET. TPS3820/3/4/8 have a watchdog timer that is periodically triggered by a positive or negative transition at WDI. When the supervising system fails to retrigger the watchdog circuit within the time-out interval, $\overline{\text{RESET}}$ becomes active for the time period t_d . This event also reinitializes the watchdog timer. Leaving WDI unconnected disables the watchdog. In applications where the input to the WDI pin may be active (transitioning high and low) when the TPS3820/3/4/8 is asserting $\overline{\text{RESET}}$, the TPS3820/3/4/8 does not return to a non-reset state when the input voltage is above V_T .

If the application requires that the WDI input is active when the RESET pin is asserted, then use the "A" version of the device. The "A" version does not latch the RESET pin to the asserted state if a WDI pulse is received while the RESET pin is asserted.

Figure 1 shows how to decouple WDI from the active signal using when using the non-"A" version. This is accomplished with an N-Channel FET in series with the WDI pin, with the gate of the FET connected to the RESET output. The "A" version of the device does not need this FET but will operate in circuits that have it. Therefore, the "A" version is backward compatible with the non""A" versions.

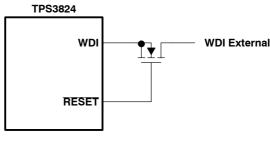


Figure 1

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in an SOT23-5 package. The TPS382x devices are characterized for operation over a temperature range of –40°C to +85°C.

PACKAGE INFORMATION(1)

DEVICE NAME	DEVICE NAME	THRESHOLD VOLTAGE(2)	MARKING
TPS3820-33DBVT ⁽³⁾	TPS3820-33DBVR(4)	2.93 V	PDEI
TPS3820-50DBVT ⁽³⁾	TPS3820-50DBVR ⁽⁴⁾	4.55 V	PDDI
TPS3823-25DBVT ⁽³⁾	TPS3823-25DBVR ⁽⁴⁾	2.25 V	PAPI
TPS3823-30DBVT ⁽³⁾	TPS3823-30DBVR ⁽⁴⁾	2.63 V	PAQI
TPS3823-33DBVT(3)	TPS3823-33DBVR(4)	2.93 V	PARI
TPS3823-50DBVT(3)	TPS3823-50DBVR(4)	4.55 V	PASI
TPS3824-25DBVT(3)	TPS3824-25DBVR(4)	2.25 V	PATI
TPS3824-30DBVT ⁽³⁾	TPS3824-30DBVR ⁽⁴⁾	2.63 V	PAUI
TPS3824-33DBVT ⁽³⁾	TPS3824-33DBVR ⁽⁴⁾	2.93 V	PAVI
TPS3824-50DBVT ⁽³⁾	TPS3824-50DBVR ⁽⁴⁾	4.55 V	PAWI
TPS3825-33DBVT(3)	TPS3825-33DBVR(4)	2.93 V	PDGI
TPS3825-50DBVT ⁽³⁾	TPS3825-50DBVR ⁽⁴⁾	4.55 V	PDFI
TPS3828-33DBVT ⁽³⁾	TPS3828-33DBVR ⁽⁴⁾	2.93 V	PDII
TPS3828-50DBVT ⁽³⁾	TPS3828-50DBVR ⁽⁴⁾	4.55 V	PDHI

⁽¹⁾ For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

⁽²⁾ For other threshold voltage versions, please contact the local TI sales office.

⁽³⁾ The DBVT package indicates tape and reel of 250 parts.

⁽⁴⁾ The DBVR package indicates tape and reel of 3000 parts.

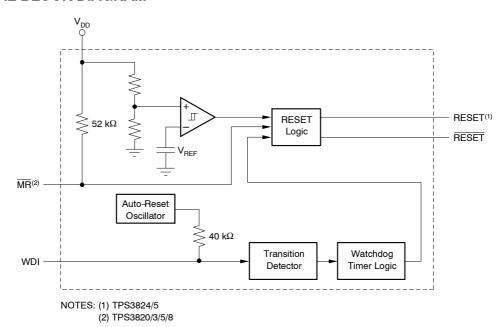


FUNCTION/TRUTH TABLE

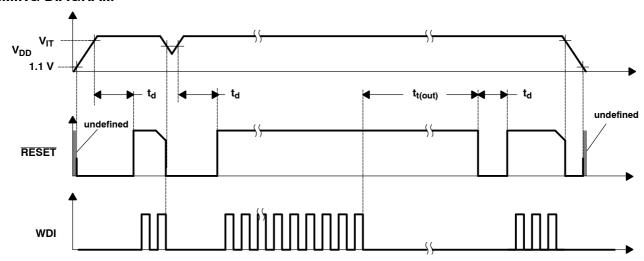
INP	UTS	OUTPUTS			
MR ⁽¹⁾	VDD > VIT	RESET	RESET(2)		
L	0	L	Н		
L	1	L	Н		
Н	0	L	Н		
Н	1	Н	L		

- (1) TPS3820/3/5/8
- (2) TPS3824/5

FUNCTIONAL BLOCK DIAGRAM



TIMING DIAGRAM









This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ABSOLUTE MAXIMUM RATINGS(1)

Over operating free-air temperature range, unless otherwise noted.

Supply voltage, V _{DD} ⁽¹⁾	
RESET, RESET, MR, WDI ⁽¹⁾	0.3 V to (V _{DD} + 0.3 V)
Maximum low output current, I _{OL}	+5 mA
Maximum high output current, I _{OH}	–5 mA
Input clamp current range, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±10 mA
Output clamp current range, I _{OK} (V _O < 0 or V _O > V _{DD})	±10 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to +85°C
Storage temperature range, T _{sta}	–65°C to +150°C
Soldering temperature	+260°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ +25°C	OPERATING FACTOR	T _A = +70°C	T _A = +85°C
	POWER RATING	ABOVE T _A = +25°C	POWER RATING	POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

RECOMMENDED OPERATING CONDITIONS

	MIN	MAX	UNIT
Supply voltage, V _{DD}	1.1	5.5	V
Input voltage, V _I	0	V _{DD} + 0.3	V
High-level input voltage at $\overline{\text{MR}}$ and WDI, V_{IH}	$0.7 \times V_{DD}$		V
Low-level input voltage, V _{IL}		$0.3 \times V_{DD}$	V
Input transition rise and fall rate at $\overline{\text{MR}}$ or WDI, $\Delta t/\Delta V$		100	ns/V
Operating free-air temperature range, T _A	-40	+85	°C

⁽²⁾ All voltage values are with respect to GND.



ELECTRICAL CHARACTERISTICS

Over operating free-air temperature range, unless otherwise noted.

	PARAMETER	₹		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
			TPS382x-25	$V_{DD} = V_{IT-} + 0.2 \text{ V}$ $I_{OH} = -20 \mu\text{A}$					
		RESET	TPS382x-30 TPS382x-33	$V_{DD} = V_{IT-} + 0.2 \text{ V}$ $I_{OH} = -30 \mu\text{A}$	0.8 × V _{DD}			V	
			TPS382x-50	$V_{DD} = V_{IT-} + 0.2 \text{ V}$ $I_{OH} = -120 \mu\text{A}$	V _{DD} – 1.5 V				
V _{OH}	High-level output voltage		TPS3824-25 TPS3825-25	$V_{DD} \ge 1.8 \text{ V}, \ I_{OH} = -100 \ \mu\text{A}$					
			TPS3824-30 TPS3825-30						
	RESET	TPS3824-33 TPS3825-33	V _{DD} ≥ 1.8 V, I _{OH} = −150 μA	$0.8 \times V_{DD}$			V		
			TPS3824-50 TPS3825-50	1					
			TPS3824-25 TPS3825-25	V _{DD} = V _{IT} + 0.2 V I _{OL} = 1 mA					
		TPS3824-30 TPS3825-30	V _{DD} = V _{IT} + 0.2 V	-					
		RESET	TPS3824-33 TPS3825-33	$I_{OL} = 1.2 \text{ mA}$			0.4	V	
V _{OL}	Low-level output voltage		TPS3824-50 TPS3825-50	$V_{DD} = V_{IT-} + 0.2 \text{ V}$ $I_{OL} = 3 \text{ mA}$					
			TPS382x-25	$V_{DD} = V_{IT-} - 0.2 V$ $I_{OL} = 1 \text{ mA}$					
		RESET	TPS382x-30 TPS382x-33	$V_{DD} = V_{IT-} - 0.2 \text{ V}$ $I_{OL} = 1.2 \text{ mA}$]		0.4	٧	
			TPS382x-50	$V_{DD} = V_{IT} - 0.2 \text{ V}$ $I_{OL} = 3 \text{ mA}$					
	Power-up reset voltage(1)	I.		$V_{DD} \ge 1.1 \text{ V}, \ I_{OL} = 20 \ \mu\text{A}$			0.4	V	
	·		TPS382x-25		2.21	2.25	2.30		
			TPS382x-30	T 000 to .0500	2.59	2.63	2.69	V	
			TPS382x-33	$T_A = 0$ °C to +85°C	2.88	2.93	3	V	
V	Negative-going input thresho	ld	TPS382x-50		4.49	4.55	4.64		
V_{IT-}	voltage ⁽²⁾		TPS382x-25		2.20	2.25	2.30		
			TPS382x-30	1000 to 10500	2.57	2.63	2.69	\ \ <i>\</i>	
			TPS382x-33	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	2.86	2.93	3	V	
			TPS382x-50		4.46	4.55	4.64		
			TPS382x-25						
V_{hys}	Hysteresis at V _{DD} input		TPS382x-30			30		mV	
▼ hys	riyotoroolo at vijiji ilipat		TPS382x-33					1117	
			TPS382x-50			50			

 ⁽¹⁾ The lowest supply voltage at which RESET becomes active. t_{r, VDD} ≥ 15 μs/V.
 (2) To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μF) should be placed near the supply terminals.



ELECTRICAL CHARACTERISTICS (continued)

Over operating free-air temperature range, unless otherwise noted.

	PARAMETER	1		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{IH(AV)}	Average high-level input curre	ent	14/51	WDI = V _{DD} , time average (dc = 88%)		120		
I _{IL(AV)}	Average low-level input curre	nt	WDI	WDI = 0.3 V, V_{DD} = 5.5 V time average (dc = 12%)		-15		
			WDI	$WDI = V_{DD}$		140	190	μΑ
I _{IH}	High-level input current		MR	$\overline{MR} = V_{DD} \times 0.7,$ $V_{DD} = 5.5 \text{ V}$		-40	-60	·
	Low-level input current		WDI	WDI = 0.3 V, V _{DD} = 5.5 V		140 190]
l _{IL}	Low-level input current	irrent M		$\overline{MR} = 0.3 \text{ V}, \ \text{V}_{DD} = 5.5 \text{ V}$		-110	-160	
			TPS382x-25					
١.	Output short-circuit	DECET	TPS382x-30	$V_{DD} = V_{IT, max} + 0.2 V,$			-400	
los	current(1)	RESET	TPS382x-33	V _O = 0 V				μ A
			TPS382x-50				-800	
I _{DD}	Supply current			WDI and MR unconnected, Outputs unconnected		15	25	μА
	Internal pullup resistor at MR			52		kΩ		
C _i	Input capacitance at MR, WD	1		V _I = 0 V to 5.5 V		5		pF

⁽¹⁾ The RESET short-circuit current is the maximum pullup current when RESET is driven low by a μP bidirectional reset pin.

TIMING REQUIREMENTS AT R_L = 1 M Ω , C_L = 50 PF, T_A = 25°C

At R_L = 1 $M\Omega$, C_L = 50 pF, T_A = +25°C.

	PARAMETER			MIN	MAX	UNIT		
		at V _{DD}	$V_{DD} = V_{IT-} + 0.2 V,$	$V_{DD} = V_{IT-} - 0.2 V$		6		μs
t _w	Pulse width	at MR	$V_{DD} \geq V_{IT-} + 0.2 \ V,$	$V_{IL} = 0.3 \times V_{DD}$	$V_{IH} = 0.7 \times V_{DD}$	1		μs
		at WDI	$V_{DD} \ge V_{IT-} + 0.2 \ V,$	$V_{IL} = 0.3 \times V_{DD}$	$V_{IH} = 0.7 \times V_{DD}$	100		ns

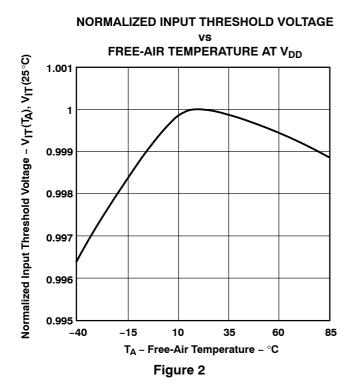
SWITCHING CHARACTERISTICS

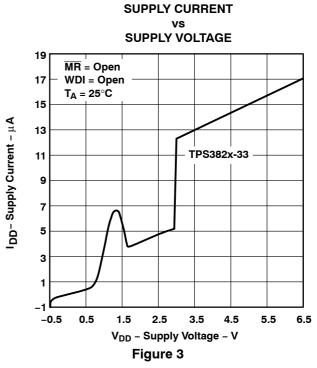
At R_L = 1 M Ω , C_L = 50 pF, T_A = +25°C.

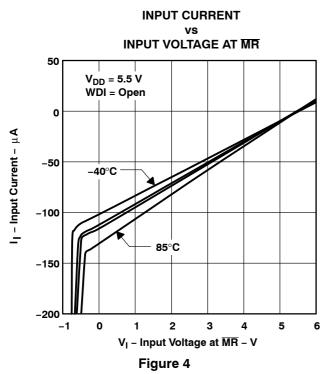
	PARAME	TER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{tout} Watchdog time out		TPS3820	$V_{DD} \ge V_{IT-} + 0.2 V$,	112	200	310	ms
t _{tout}	watchdog time out	TPS3823/4/8	See timing diagram	0.9	1.6	2.5	S
	Dala Para	TPS3820	$V_{DD} \ge V_{IT-} + 0.2 V$,	15	25	37	
t _d	Delay time	TPS3823/4/5/8	See timing diagram	120	200	300	ms
t _{PHL}	Propagation (delay) time,	MR to RESET delay (TPS3820/3/5/8)	$\begin{aligned} &V_{DD} \ge V_{IT_{-}} + 0.2 \ V, \\ &V_{IL} = 0.3 \ x \ V_{DD}, \\ &V_{IH} = 0.7 \ x \ V_{DD} \end{aligned}$			0.1	μs
	high-to-low-level output	V _{DD} to RESET delay	$V_{IL} = V_{IT-} - 0.2 V,$ $V_{IH} = V_{IT-} + 0.2 V$	25			·
t _{PLH}	Propagation (delay) time, low-to-high-level output	MR to RESET delay (TPS3824/5)	$V_{DD} \ge V_{IT-} + 0.2 \text{ V},$ $V_{IL} = 0.3 \text{ x } V_{DD},$ $V_{IH} = 0.7 \text{ x } V_{DD}$			0.1	μs
	iow-to-mgn-level output	V _{DD} to RESET delay (TPS3824/5)	$V_{IL} = V_{IT-} - 0.2 \text{ V},$ $V_{IH} = V_{IT-} + 0.2 \text{ V}$			25	

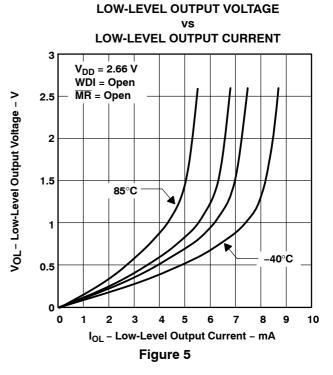


TYPICAL CHARACTERISTICS



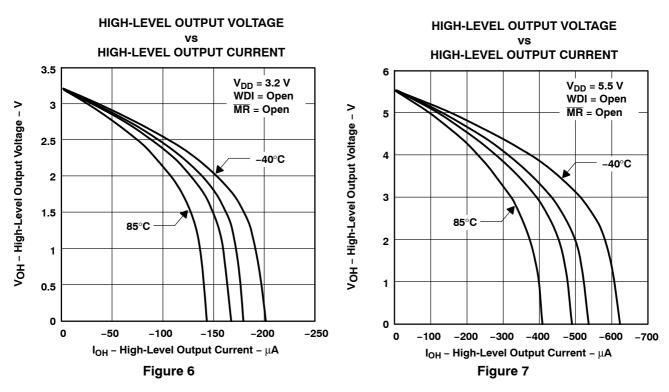




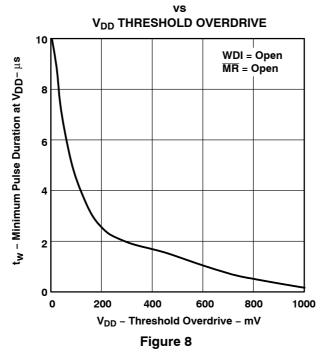




TYPICAL CHARACTERISTICS







Revision History

DATE	REV	PAGE	SECTION	DESCRIPTION
1/08	G	2	Description	Deleted last paragraph.
1/08	G	3	Functional Block Diagram	Replaced diagram.
6/07		Front Page	_	Updated front page.
0/07	6/07 F 3		Function/Truth Table	Corrected Note (2) from PS3820/3/5/8 to TPS3824/5.
7/2012	Н	1	Titles/Pin labels	Added "A" to the device numbers in headers and to the pin Packages. Also changed the Lit rev letter to H, July 2012
7/2012	Н	2	Description (continued)	Deleted last sentence in paragraph and replaced with new text also added new paragraph.

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TPS3820-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3820-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3820-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3820-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3820-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3820-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3820-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3820-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-25DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-25DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-25DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-25DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-30DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-30DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-30DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-30DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TPS3823-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3823-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-25DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-25DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-25DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-25DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-30DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-30DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-30DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-30DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TPS3824-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3824-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3825-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3825-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3825-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3825-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3825-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3825-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3825-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3825-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3828-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3828-33DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3828-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3828-33DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3828-50DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	





www.ti.com 17-Jul-2012

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TPS3828-50DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3828-50DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3828-50DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TPS3820-33, TPS3820-50, TPS3823-25, TPS3823-30, TPS3823-30, TPS3823-50, TPS3824-25, TPS3824-30, TPS3824-30, TPS3824-50, TPS3825-33, TPS3825-50, TPS3828-33, TPS3828-33, TPS3828-30, TP

Automotive: TPS3820-33-Q1, TPS3820-50-Q1, TPS3823-25-Q1, TPS3823-30-Q1, TPS3823-33-Q1, TPS3823-50-Q1, TPS3824-25-Q1, TPS3824-30-Q1, TPS3824-30-Q1, TPS3824-50-Q1, TPS3824-50-Q1





NOTE: Qualified Version Definitions:

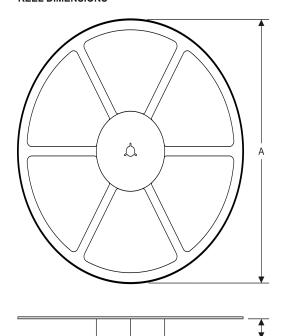
• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

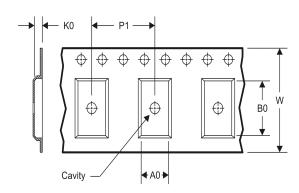
www.ti.com 17-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

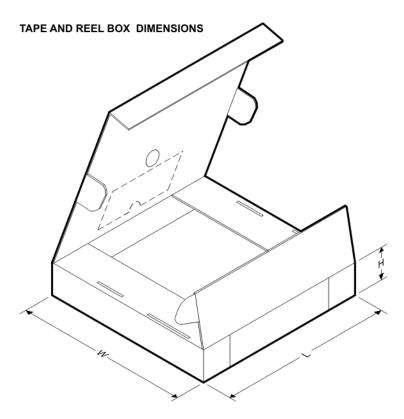
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3820-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3820-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3820-50DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3820-50DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3823-25DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-25DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3823-25DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-25DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3823-30DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-30DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3823-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-25DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-25DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-30DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-30DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

www.ti.com 17-Jul-2012

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3824-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3824-50DBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3824-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3825-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3825-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3825-50DBVR	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3825-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3828-33DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3828-33DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3828-50DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3828-50DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3820-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3820-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3820-50DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3820-50DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0



PACKAGE MATERIALS INFORMATION

www.ti.com 17-Jul-2012

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3823-25DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823-25DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3823-25DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-25DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3823-30DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823-30DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3823-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3823-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3823-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3824-25DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3824-25DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3824-30DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3824-30DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3824-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3824-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3824-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3824-50DBVT	SOT-23	DBV	5	250	203.0	203.0	35.0
TPS3824-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3825-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3825-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3825-50DBVR	SOT-23	DBV	5	3000	203.0	203.0	35.0
TPS3825-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3828-33DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3828-33DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
TPS3828-50DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
TPS3828-50DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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